

CLAIMS

What is claimed is:

1. A method for fabricating at least one emission structure, comprising:
forming at least one conductive structure extending across at least a portion of a substrate;
substantially removing a longitudinal portion of said at least one conductive structure to define at least one conductive layer substantially perpendicular to said substrate, said substrate being exposed along a length of said at least one conductive layer; and
forming at least one emission structure adjacent said at least one conductive layer.
2. The method of claim 1, wherein said forming said at least one emission structure includes forming an emitter tip.
3. The method of claim 2, wherein said forming said at least one emission structure further includes forming a resistor corresponding to said at least one emitter tip.
4. The method of claim 3, wherein said forming said resistor comprises forming said resistor adjacent to said at least one conductive layer.
5. The method of claim 1, wherein said forming said at least one emission structure comprises forming a plurality of lines of emission structures.
6. The method of claim 5, wherein said substantially removing comprises electrically isolating at least one emission structure located along a first line of said plurality of lines from at least one emission structure located along an adjacent, second line of said plurality of lines.

7. The method of claim 1, wherein said forming said at least one conductive structure comprises:
disposing a layer comprising conductive material over said substrate; and
patterning said layer.
8. The method of claim 1, wherein said forming said at least one emission structure comprises forming said at least one emission structure from at least one of semiconductive material and conductive material.
9. The method of claim 1, wherein said forming said at least one emission structure comprises forming said at least one emission structure so as to extend over a lateral edge of said at least one conductive structure.
10. A method for fabricating at least one emission structure, comprising:
forming at least one conductive structure that extends at least partially across a substrate;
forming at least one emitter tip and a corresponding resistor adjacent to said at least one conductive structure; and
substantially removing at least a longitudinal portion of said at least one conductive structure along substantially an entire length thereof to define at least one conductive layer substantially perpendicular to said substrate.
11. The method of claim 10, wherein said forming said at least one conductive structure comprises:
disposing a layer comprising conductive material on said substrate; and
patterning said layer.
12. The method of claim 10, wherein said forming said at least one emitter tip comprises forming said at least one emitter tip from at least one of semiconductive material and conductive material.

13. The method of claim 10, wherein said forming said corresponding resistor comprises forming said corresponding resistor from at least one of semiconductive material and conductive material.

14. The method of claim 10, wherein said forming said at least one emitter tip comprises:
disposing at least one layer comprising at least one of semiconductive material and conductive material over said substrate and said at least one conductive structure;
removing a longitudinal portion of at least one region of said at least one layer located over said at least one conductive structure to expose at least a substantially longitudinal portion of said at least one conductive structure; and
patterning at least one remaining portion of said at least one layer.

15. The method of claim 14, wherein said patterning said at least one remaining portion of said at least one layer includes defining said at least one emitter tip from said at least one layer.

16. The method of claim 15, wherein said patterning said at least one remaining portion of said at least one layer further includes forming said corresponding resistor.

17. The method of claim 10, wherein said substantially removing comprises leaving at least a lateral edge of said at least one conductive structure along substantially said entire length thereof.

18. The method of claim 10, wherein said forming said at least one emitter tip comprises forming said at least one emitter tip so as to extend over a lateral edge of said at least one conductive structure.